

2SD1576

Silicon NPN Triple-Diffused Junction Mesa Type

Horizontal Deflection Output

■ Features

- High breakdown voltage and high reliability by glass passivation
- High speed switching
- Wide area of safety operation (ASO)
- "Full Pack" package for simplified mounting on a heat sink with one screw

■ Absolute Maximum Ratings (Tc=25°C)

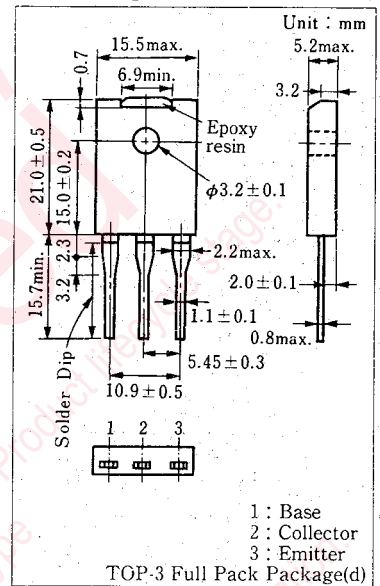
Item	Symbol	Value	Unit	
Collector-base voltage	V _{CB0}	1500	V	
Collector-emitter voltage	V _{CES}	1500	V	
	V _{CEO}	700	V	
Emitter-base voltage	V _{EBO}	6	V	
Collector current	I _C	2	A	
Peak collector current	I _{CP} *	6	A	
Peak base current	I _{BP}	2.5	A	
Reverse peak base current	I _{BP}	-1.5	A	
Collector power dissipation	P _C	T _c =25°C	80	W
		T _a =25°C	2.5	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 ~ +150	°C	

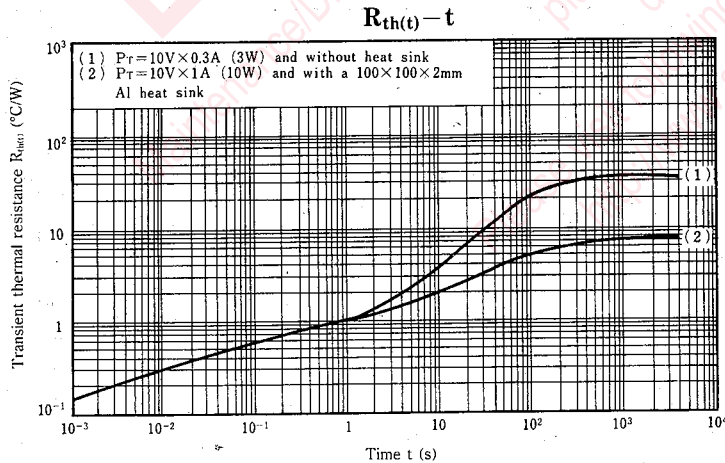
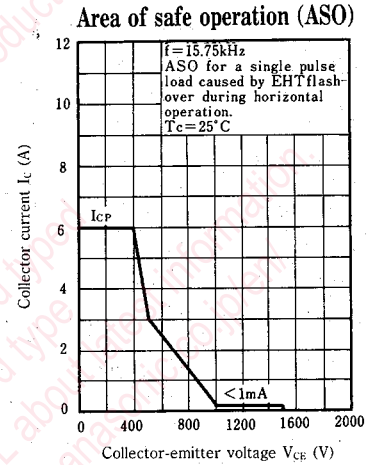
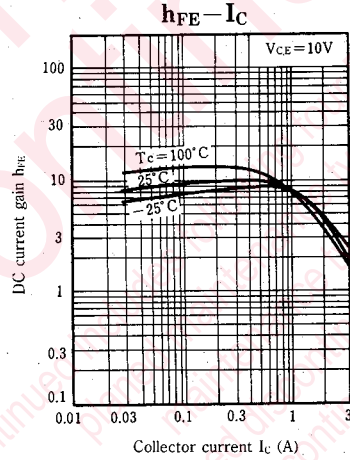
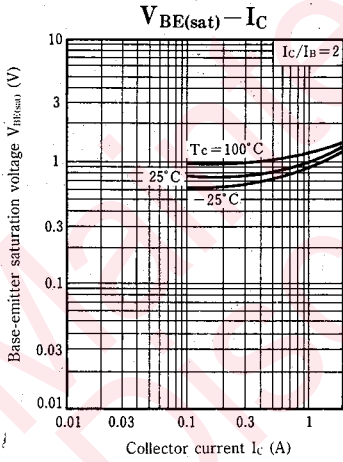
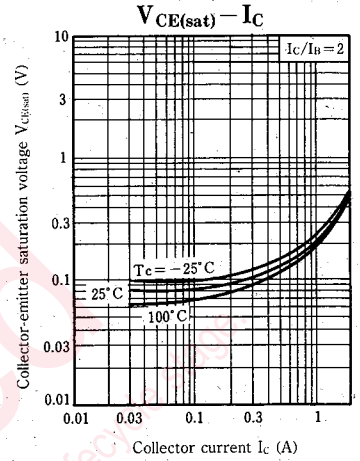
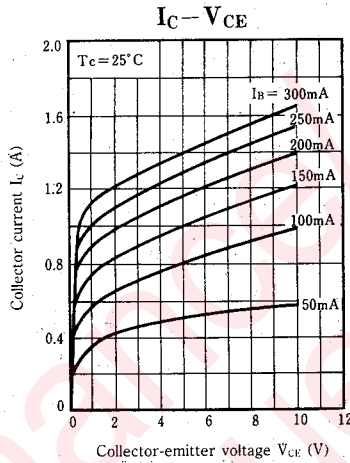
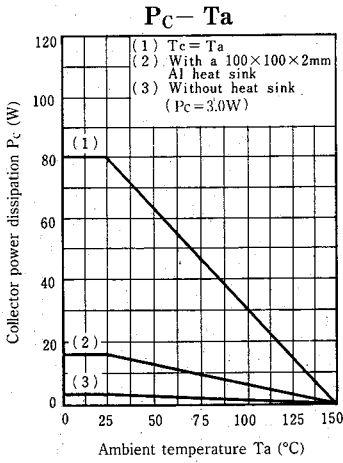
* Non repetitive peak value

■ Electrical Characteristics (Tc=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Collector cutoff current	I _{CB0}	V _{CB} =750V, I _E =0			50	μA
		V _{CB} =1500V, I _E =0			1	mA
Emitter-base voltage	V _{EBO}	I _E =1mA, I _C =0	6			V
DC current gain	h _{FE}	V _{CE} =5V, I _C =2A	2		5	
Collector-emitter saturation voltage	V _{CE(sat)}	I _C =2A, I _B =1A			5	V
Base-emitter saturation voltage	V _{BE(sat)}	I _C =2A, I _B =1A			1.5	V
Transition frequency	f _T	V _{CE} =10V, I _C =0.5A, f=0.5MHz		2		MHz
Fall time	t _f	I _C =2.5A, I _{Bend} =1.1A			1	μs
Storage time	t _{stg}	L _B =10μH			9	μs

■ Package Dimensions





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